

L Number	Hits	Search Text	DB	Time stamp
1	258	438/758.ccls. and hydrogen	USPAT; US-PGPUB	2004/09/23 10:02
2	20	(438/758.ccls. and hydrogen) and plat\$3 and nickel	USPAT; US-PGPUB	2004/09/23 10:01
3	1	438/761.ccls. and hydrogen and nickel with bath	USPAT; US-PGPUB	2004/09/23 10:02
-	592162	hydrogen or "h.sub.2"	USPAT; US-PGPUB	2004/09/23 10:00
-	1814	(hydrogen or "h.sub.2") adj saturat\$4	USPAT; US-PGPUB	2004/08/26 16:05
-	866	((hydrogen or "h.sub.2") adj saturat\$4) and plat\$4	USPAT; US-PGPUB	2004/08/26 14:53
-	66	((hydrogen or "h.sub.2") adj saturat\$4) and plat\$4) and semiconductor	USPAT; US-PGPUB	2004/08/26 15:47
-	12609	electroless adj plat\$4	USPAT; US-PGPUB	2004/09/13 15:57
-	272	(electroless adj plat\$4) near6 semiconduct\$3	USPAT; US-PGPUB	2004/08/26 15:15
-	0	((electroless adj plat\$4) near6 semiconduct\$3) and nickle near4 bath	USPAT; US-PGPUB	2004/08/26 15:15
-	0	((electroless adj plat\$4) near6 semiconduct\$3) and nickal near4 bath	USPAT; US-PGPUB	2004/08/26 15:15
-	25	((electroless adj plat\$4) near6 semiconduct\$3) and nickel near4 bath	USPAT; US-PGPUB	2004/08/26 15:15
-	14	((electroless adj plat\$4) near6 semiconduct\$3) and nickel near4 bath) and (hydrogen or "h.sub.2")	USPAT; US-PGPUB	2004/09/16 09:11
-	4	(((hydrogen or "h.sub.2") adj saturat\$4) and plat\$4) and semiconductor) and nickel near6 bath	USPAT; US-PGPUB	2004/08/26 15:47
-	16	(hydrogen adj saturation) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:17
-	2	2001/0035452	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/26 16:16
-	4	2001/0033020	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/26 16:19
-	173	hydrogen adj saturation	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/27 15:49
-	45	hydrogen adj saturation and plat\$6 near6 nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:07

	9	<b>hydrogen near3 saturat\$4 and plat\$6 near5 nickel near4 bath</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b> <b>USPAT</b>	2004/08/27 16:09
	2	("4789452"   "4877508").PN.	<b>USPAT</b>	2004/08/27 16:08
	3	<b>4877508.URPN.</b>	<b>USPAT</b>	2004/08/27 16:08
	18	<b>hydrogen near3 saturat\$4 and nickel near4 bath</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b> <b>USPAT;</b>	2004/08/27 16:13
	50	<b>hydrogen with saturat\$4 and nickel near4 bath</b>	<b>US-PGPUB; EPO; JPO; DERWENT</b> <b>USPAT;</b>	2004/09/10 11:22
	434	<b>427/438.ccIs.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b> <b>USPAT;</b>	2004/09/10 11:22
	64	<b>427/438.ccIs. and semiconductor</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b> <b>USPAT;</b>	2004/09/10 11:38
	56	"3403035"	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b> <b>USPAT;</b>	2004/09/10 12:00
	38	<b>3403035.URPN.</b>	<b>USPAT</b>	2004/09/10 11:40
	700	<b>438/678.ccIs.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b> <b>USPAT;</b>	2004/09/21 14:42
	120	<b>438/678.ccIs. and nickel near6 plating</b>	<b>US-PGPUB; EPO; JPO; DERWENT</b> <b>USPAT;</b>	2004/09/16 09:17
	42	<b>copper adj coat\$3 near2 \$wafer</b>	<b>US-PGPUB; EPO; JPO; DERWENT</b> <b>USPAT;</b>	2004/09/21 14:42
	912902	<b>hydrogen or "h.sub.2"</b>	<b>US-PGPUB; EPO; JPO; DERWENT</b> <b>USPAT;</b>	2004/09/13 15:58
	1445	<b>(hydrogen or "h.sub.2") and 427/43\$.ccIs.</b>	<b>US-PGPUB; EPO; JPO; DERWENT</b> <b>USPAT;</b>	2004/09/13 15:59
	831	<b>(hydrogen or "h.sub.2") and 427/43\$.ccIs. and plat\$3</b>	<b>US-PGPUB; EPO; JPO; DERWENT</b> <b>USPAT;</b>	2004/09/13 16:00

	33	<b>(hydrogen or "h.sub.2") and 427/43\$.ccls. and plat\$3 with (nickel adj bath)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/13 16:10</b>
	4	<b>nickel adj bath and dummy adj (metal plat\$3)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/13 16:08</b>
	0	<b>427/98.ccls.</b>	<b>USPAT; US-PGPUB</b>	<b>2004/09/14 09:49</b>
	899	<b>427/405.ccls.</b>	<b>USPAT; US-PGPUB</b>	<b>2004/09/13 16:17</b>
	26	<b>427/405.ccls. and nickel adj bath</b>	<b>USPAT; US-PGPUB</b>	<b>2004/09/13 16:18</b>
	626	<b>427/436.ccls.</b>	<b>USPAT; US-PGPUB</b>	<b>2004/09/13 16:18</b>
	12	<b>427/436.ccls. and nickel adj bath</b>	<b>USPAT; US-PGPUB</b>	<b>2004/09/14 09:16</b>
	1523	<b>(copper Cu) adj (coat\$3 layer film) near2 (semiconductor or conductor \$wafer)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/13 16:20</b>
	35	<b>((copper Cu) adj (coat\$3 layer film) near2 (semiconductor or conductor \$wafer)) with (nickel or Ni)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/13 16:21</b>
	13	<b>427/436.ccls. and nickel adj bath</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/16 09:11</b>
	111	<b>427/43\$.ccls. and nickel adj bath</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/14 09:38</b>
	70	<b>427/43\$.ccls. and copper adj plate</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/14 09:38</b>
	446	<b>427/98.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/14 09:49</b>
	0	<b>427/98.ccls. and nickel adj bath</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/14 09:49</b>
	64	<b>427/98.ccls. and (nickel or Ni)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/14 09:50</b>
	14	<b>((electroless adj plat\$4) near6 semiconductor\$3) and nickel near4 bath) and (hydrogen or "h.sub.2")</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/16 09:12</b>

	159	<b>427/436.ccls. and nickel</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/16 09:17</b>
	87	<b>((electroless adj plat\$4) near6 semiconduct\$3) and nickel) and (hydrogen or "h.sub.2")</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/16 09:12</b>
	60	<b>427/436.ccls. and nickel and hydrogen</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/16 09:17</b>
	5	<b>hydrogen adj saturation and nickel adj bath</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:08</b>
	3	<b>hydrogen adj saturation with plat\$3 near3 nickel</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:08</b>
	0	<b>(hydrogen adj saturation) and 438/687.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:17</b>
	516	<b>hydrogen and 438/687.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:18</b>
	3	<b>hydrogenation and 438/687.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:37</b>
	12726	<b>saturated near2 hydrogen</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:37</b>
	30	<b>saturated near2 hydrogen with nickel</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:40</b>
	48	<b>saturat\$4 near2 hydrogen with nickel</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:42</b>
	20	<b>(saturat\$4 near2 hydrogen with nickel ) not (saturated near2 hydrogen with nickel )</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:41</b>
	1	<b>saturat\$4 near2 hydrogen and 438/687.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:43</b>

-	5	<b>saturat\$4 near2 hydrogen with copper with nickel</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:55</b>
-	1376	<b>427/304.ccls. or 427/305.ccls. and nickel adj bath</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:56</b>
-	349	<b>(427/304.ccls. or 427/305.ccls. and nickel adj bath) and hydrogen</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:56</b>
-	298	<b>((427/304.ccls. or 427/305.ccls. and nickel adj bath) and hydrogen) and copper</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:56</b>
-	1	<b>(427/304.ccls. or 427/305.ccls. and nickel adj bath) and hydrogen adj (saturation or saturated)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:57</b>
-	15	<b>(427/304.ccls. or 427/305.ccls. and nickel adj bath) and (hydrogen adj (saturation or saturated) or hydrogenation)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT</b>	<b>2004/09/21 14:57</b>